

ABSTRACT OF THE DISCLOSURE

An electronic substrate is used to mount a plurality of semiconductor chips thereon. The substrate includes a first conductive member, a second conductive member, and an insulating layer. The first conductive member is electrically connected to one of the semiconductor chips. The second conductive member is electrically connected to another one of the semiconductor chips. The insulating layer is arranged to electrically isolate the second conductive member from the first conductive member. The first conductive member is a conductive base that supports the insulating layer, the semiconductor chips and the second conductive member thereon.